

## FEATURES

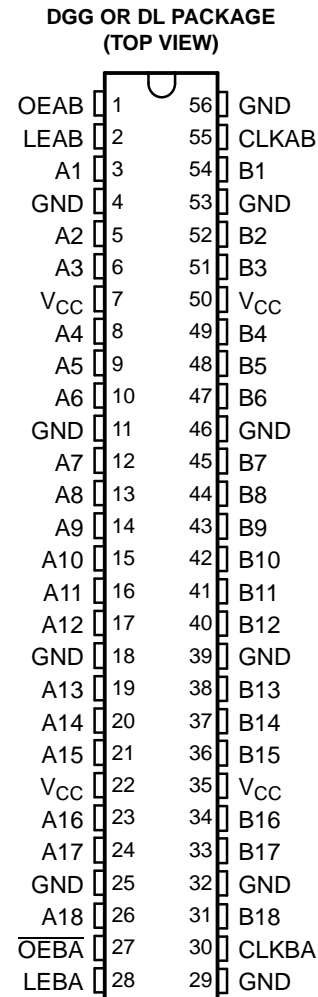
- Member of the Texas Instruments Widebus™ Family
- UBT™ Transceiver Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, or Clocked Modes
- Operates From 1.65 V to 3.6 V
- Max  $t_{pd}$  of 3.9 ns at 3.3 V
- $\pm 24$ -mA Output Drive at 3.3 V
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

## DESCRIPTION/ORDERING INFORMATION

This 18-bit universal bus transceiver is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

Data flow in each direction is controlled by output-enable ( $\overline{OEAB}$  and  $\overline{OEBA}$ ), latch-enable ( $\overline{LEAB}$  and  $\overline{LEBA}$ ), and clock ( $\overline{CLKAB}$  and  $\overline{CLKBA}$ ) inputs. For A-to-B data flow, the device operates in the transparent mode when  $\overline{LEAB}$  is high. When  $\overline{LEAB}$  is low, the A data is latched if  $\overline{CLKAB}$  is held at a high or low logic level. If  $\overline{LEAB}$  is low, the A data is stored in the latch/flip-flop on the low-to-high transition of  $\overline{CLKAB}$ . When  $\overline{OEAB}$  is high, the outputs are active. When  $\overline{OEAB}$  is low, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B, but uses  $\overline{OEBA}$ ,  $\overline{LEBA}$ , and  $\overline{CLKBA}$ . The output enables are complementary ( $\overline{OEAB}$  is active high, and  $\overline{OEBA}$  is active low).



## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP - DL	Tube	SN74ALVCH16501DL	ALVCH16501
		Tape and reel	SN74ALVCH16501DLR	
	TSSOP - DGG	Tape and reel	SN74ALVCH16501DGGR	ALVCH16501
	VFBGA - GQL	Tape and reel	SN74ALVCH16501KR	VH501
VFBGA - ZQL (Pb-free)	74ALVCH16501ZQLR			

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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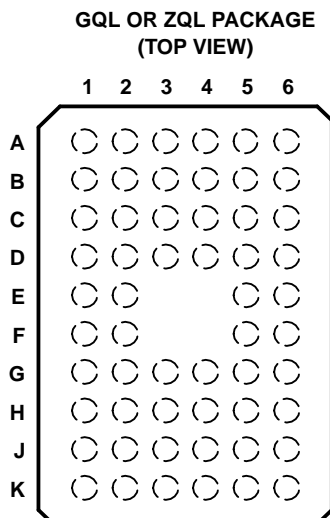
**SN74ALVCH16501**  
**18-BIT UNIVERSAL BUS TRANSCEIVER**  
**WITH 3-STATE OUTPUTS**

SCES024J–JULY 1995–REVISED OCTOBER 2004

**DESCRIPTION/ORDERING INFORMATION (CONTINUED)**

To ensure the high-impedance state during power up or power down,  $\overline{OEBA}$  should be tied to  $V_{CC}$  through a pullup resistor, and OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.



**TERMINAL ASSIGNMENTS**

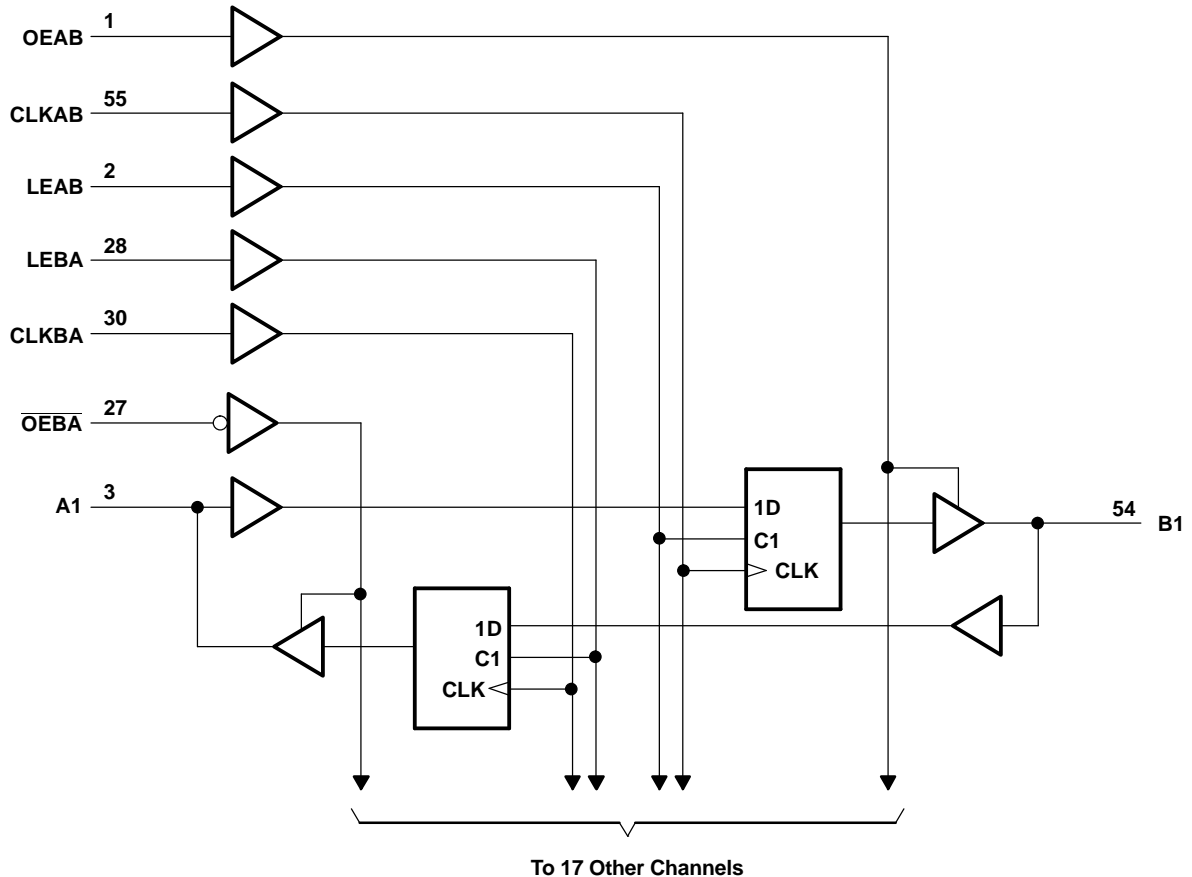
	1	2	3	4	5	6
<b>A</b>	A1	LEAB	OEAB	GND	CLKAB	B1
<b>B</b>	A3	A2	GND	GND	B2	B3
<b>C</b>	A5	A4	$V_{CC}$	$V_{CC}$	B4	B5
<b>D</b>	A7	A6	GND	GND	B6	B7
<b>E</b>	A9	A8			B8	B9
<b>F</b>	A10	A11			B11	B10
<b>G</b>	A12	A13	GND	GND	B13	B12
<b>H</b>	A14	A15	$V_{CC}$	$V_{CC}$	B15	B14
<b>J</b>	A16	A17	GND	GND	B17	B16
<b>K</b>	A18	$\overline{OEBA}$	LEBA	GND	CLKBA	B18

**FUNCTION TABLE<sup>(1)</sup>**

INPUTS				OUTPUT B
OEAB	LEAB	CLKAB	A	
L	X	X	X	Z
H	H	X	L	L
H	H	X	H	H
H	L	↑	L	L
H	L	↑	H	H
H	L	H	X	B <sub>0</sub> <sup>(2)</sup>
H	L	L	X	B <sub>0</sub> <sup>(3)</sup>

- (1) A-to-B data flow is shown; B-to-A flow is similar, but uses  $\overline{OEBA}$ ,  $\overline{LEBA}$ , and  $\overline{CLKBA}$ .
- (2) Output level before the indicated steady-state input conditions were established, provided that  $\overline{CLKAB}$  was high before  $\overline{LEAB}$  went low
- (3) Output level before the indicated steady-state input conditions were established

**LOGIC DIAGRAM (POSITIVE LOGIC)**



Pin numbers shown are for the DGG and DL packages.

# SN74ALVCH16501

## 18-BIT UNIVERSAL BUS TRANSCEIVER WITH 3-STATE OUTPUTS

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### ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	-0.5	4.6	V
V <sub>I</sub>	Input voltage range	Except I/O ports <sup>(2)</sup>		V
		I/O ports <sup>(2)(3)</sup>	V <sub>CC</sub> + 0.5	
V <sub>O</sub>	Output voltage range <sup>(2)(3)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50
I <sub>O</sub>	Continuous output current			±50
	Continuous current through each V <sub>CC</sub> or GND			±100
θ <sub>JA</sub>	Package thermal impedance <sup>(4)</sup>	DGG package		64
		DL package		56
		GQL/ZQL package		42
T <sub>stg</sub>	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

### RECOMMENDED OPERATING CONDITIONS<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	1.65	3.6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7	
		V <sub>CC</sub> = 2.7 V to 3.6 V	2	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.35 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.7	
		V <sub>CC</sub> = 2.7 V to 3.6 V	0.8	
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 1.65 V	-4	mA
		V <sub>CC</sub> = 2.3 V	-12	
		V <sub>CC</sub> = 2.7 V	-12	
		V <sub>CC</sub> = 3 V	-24	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V	4	mA
		V <sub>CC</sub> = 2.3 V	12	
		V <sub>CC</sub> = 2.7 V	12	
		V <sub>CC</sub> = 3 V	24	
Δt/Δv	Input transition rise or fall rate		10	ns/V
T <sub>A</sub>	Operating free-air temperature	-40	85	°C

- (1) All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2			V
	I <sub>OH</sub> = -4 mA	1.65 V	1.2			
	I <sub>OH</sub> = -6 mA	2.3 V	2			
	I <sub>OH</sub> = -12 mA	2.3 V	1.7			
		2.7 V	2.2			
		3 V	2.4			
I <sub>OH</sub> = -24 mA	3 V	2				
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V	0.2			V
	I <sub>OL</sub> = 4 mA	1.65 V	0.45			
	I <sub>OL</sub> = 6 mA	2.3 V	0.4			
	I <sub>OL</sub> = 12 mA	2.3 V	0.7			
		2.7 V	0.4			
	I <sub>OL</sub> = 24 mA	3 V	0.55			
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V	±5			μA
I <sub>I(hold)</sub>	V <sub>I</sub> = 0.58 V	1.65 V	25			μA
	V <sub>I</sub> = 1.07 V	1.65 V	-25			
	V <sub>I</sub> = 0.7 V	2.3 V	45			
	V <sub>I</sub> = 1.7 V	2.3 V	-45			
	V <sub>I</sub> = 0.8 V	3 V	75			
	V <sub>I</sub> = 2 V	3 V	-75			
	V <sub>I</sub> = 0 V to 3.6 V <sup>(2)</sup>	3.6 V	±500			
I <sub>OZ</sub> <sup>(3)</sup>	V <sub>O</sub> = V <sub>CC</sub> or GND	3.6 V	±10			μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V	40			μA
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V	750			μA
C <sub>i</sub>	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	4			pF
C <sub>io</sub>	A or B ports	V <sub>O</sub> = V <sub>CC</sub> or GND	8			pF

(1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

(3) For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

## TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX		
f <sub>clock</sub>	Clock frequency	150		150		150		MHz	
t <sub>w</sub>	Pulse duration	LE high		3.3		3.3		ns	
		CLK high or low		3.3		3.3			
t <sub>su</sub>	Setup time	Data before CLK↑		2.2		2.1		ns	
		Data before LE↓	CLK high		1.9		1.6		
			CLK low		1.3		1.1		
t <sub>h</sub>	Hold time	Data after CLK↑		0.6		0.6		ns	
		Data after LE↓	CLK high or low		1.4		1.7		

**SN74ALVCH16501**  
**18-BIT UNIVERSAL BUS TRANSCEIVER**  
**WITH 3-STATE OUTPUTS**

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**SWITCHING CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

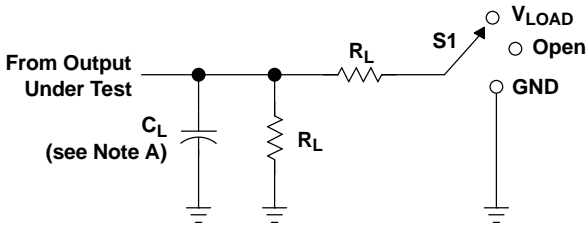
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
$f_{max}$			150		150		150		MHz
$t_{pd}$	A or B	B or A	1	4.8		4.5	1	3.9	ns
	LE	A or B	1.1	5.7		5.3	1.3	4.6	
	CLK		1.2	6.1		5.6	1.4	4.9	
$t_{en}$	OEAB	B	1	5.8		5.3	1	4.6	ns
$t_{dis}$	OEAB	B	1.5	6.2		5.7	1.4	5	ns
$t_{en}$	$\overline{OEBA}$	A	1.3	6.3		6	1.1	5	ns
$t_{dis}$	$\overline{OEBA}$	A	1.3	5.3		4.6	1.3	4.2	ns

**OPERATING CHARACTERISTICS**

$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	UNIT
			TYP	TYP	
$C_{pd}$	Power dissipation capacitance	$C_L = 50\text{ pF}, f = 10\text{ MHz}$	44	54	pF
			Outputs enabled	6	
	Outputs disabled				

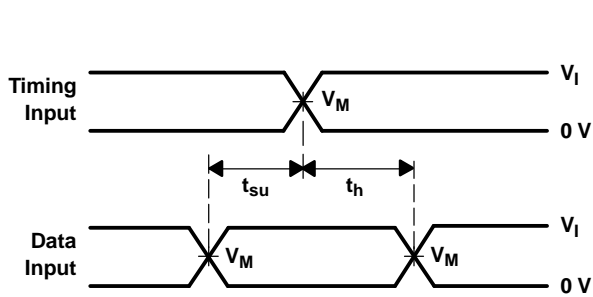
PARAMETER MEASUREMENT INFORMATION



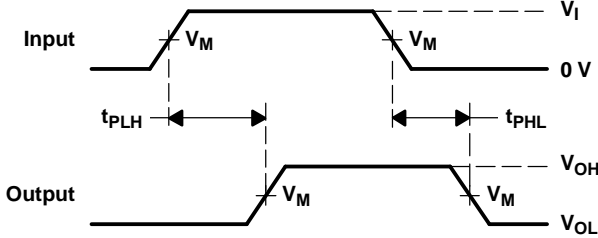
LOAD CIRCUIT

TEST	S1
$t_{pd}$ $t_{PLZ}/t_{PZL}$ $t_{PHZ}/t_{PZH}$	Open $V_{LOAD}$ GND

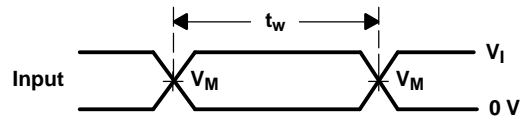
$V_{CC}$	INPUT		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
1.8 V	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
2.5 V $\pm$ 0.2 V	$V_{CC}$	$\leq 2$ ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
2.7 V	2.7 V	$\leq 2.5$ ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	$\leq 2.5$ ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V



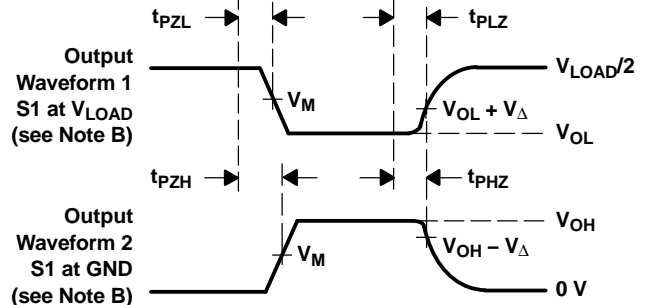
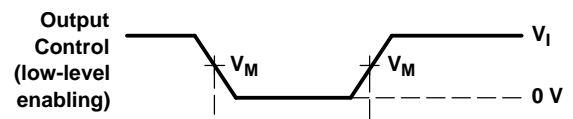
VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74ALVCH16501DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16501	<a href="#">Samples</a>
74ALVCH16501DLRG4	ACTIVE	SSOP	DL	56		TBD	Call TI	Call TI	-40 to 85		<a href="#">Samples</a>
74ALVCH16501ZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	VH501	<a href="#">Samples</a>
SN74ALVCH16501DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16501	<a href="#">Samples</a>
SN74ALVCH16501DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16501	<a href="#">Samples</a>
SN74ALVCH16501DLR	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI	-40 to 85		
SN74ALVCH16501KR	OBSOLETE	BGA MICROSTAR JUNIOR	GQL	56		TBD	Call TI	Call TI	-40 to 85		

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ALVCH16501ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1
SN74ALVCH16501DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

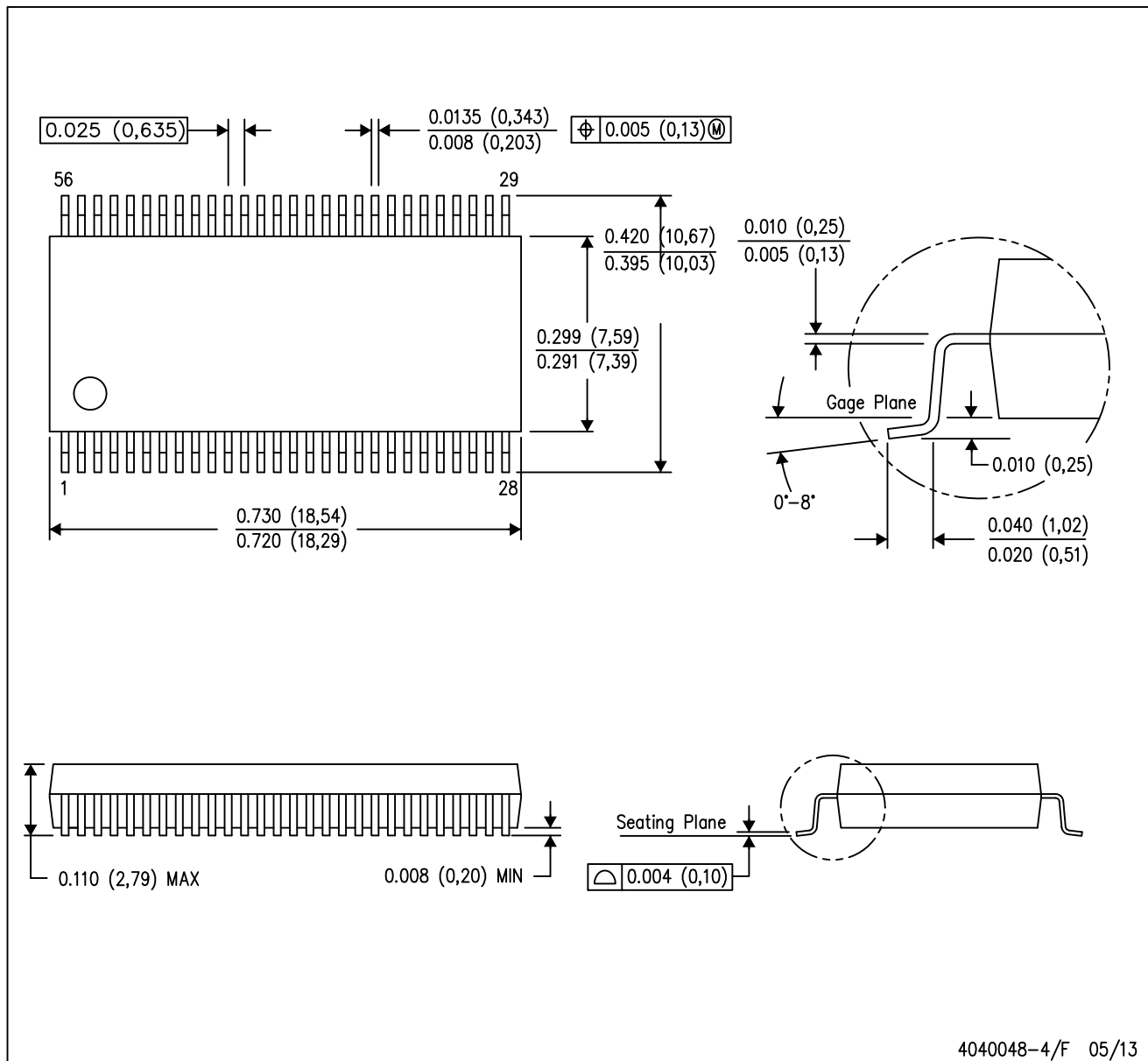

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ALVCH16501ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	333.2	345.9	28.6
SN74ALVCH16501DGGR	TSSOP	DGG	56	2000	367.0	367.0	45.0

# MECHANICAL DATA

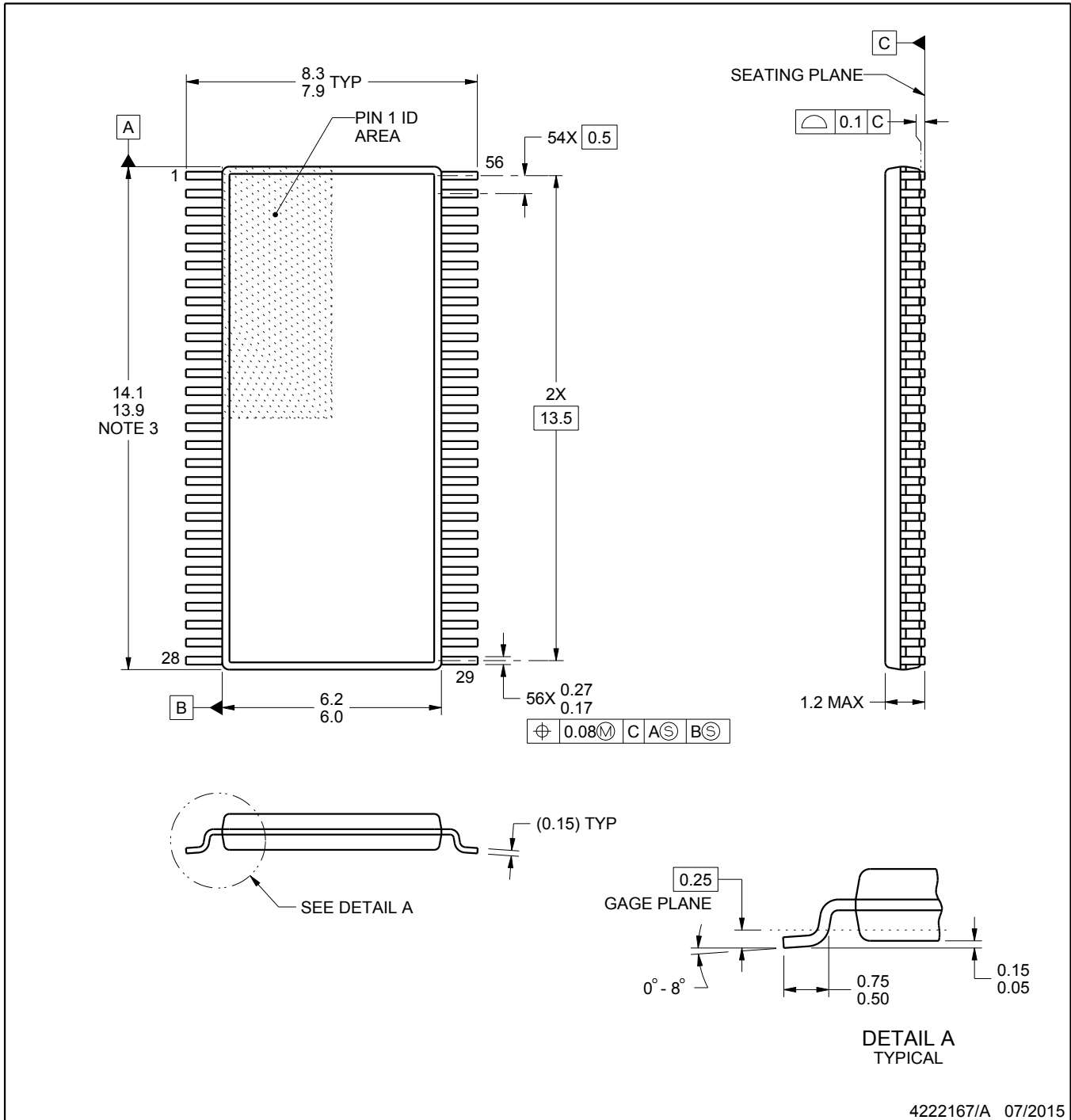
DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



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NOTES:

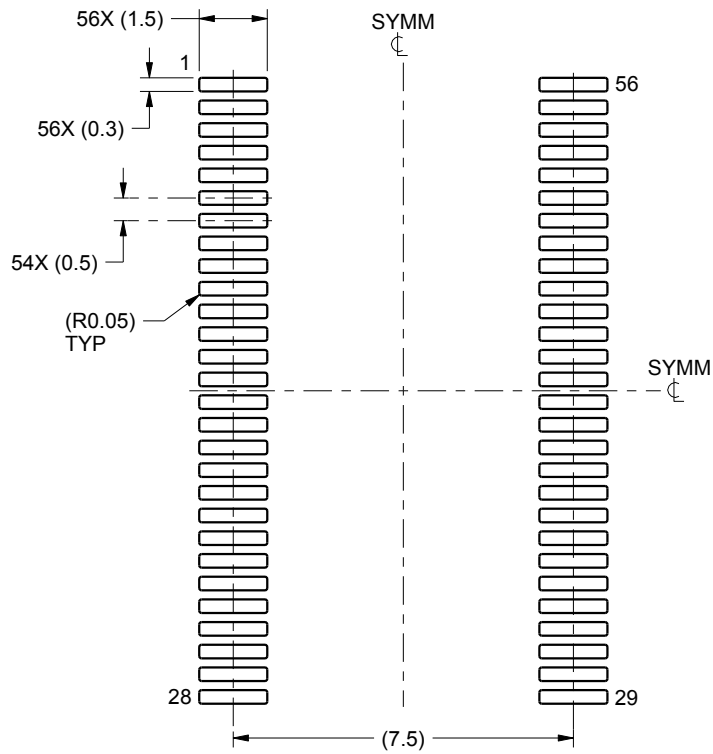
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

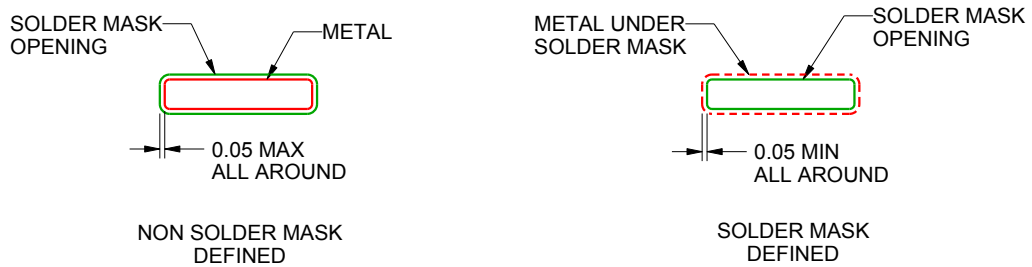
DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4222167/A 07/2015

NOTES: (continued)

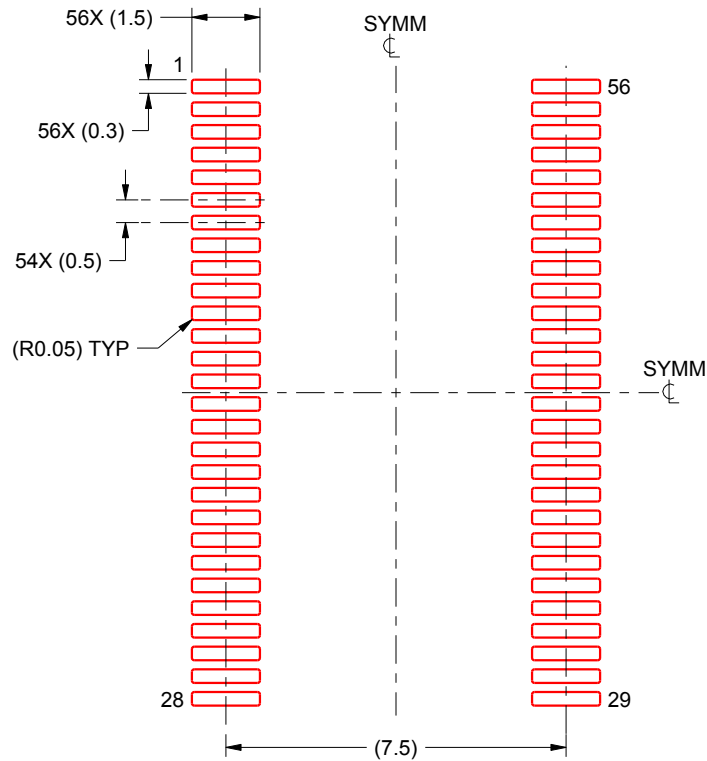
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



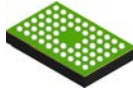
SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4222167/A 07/2015

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

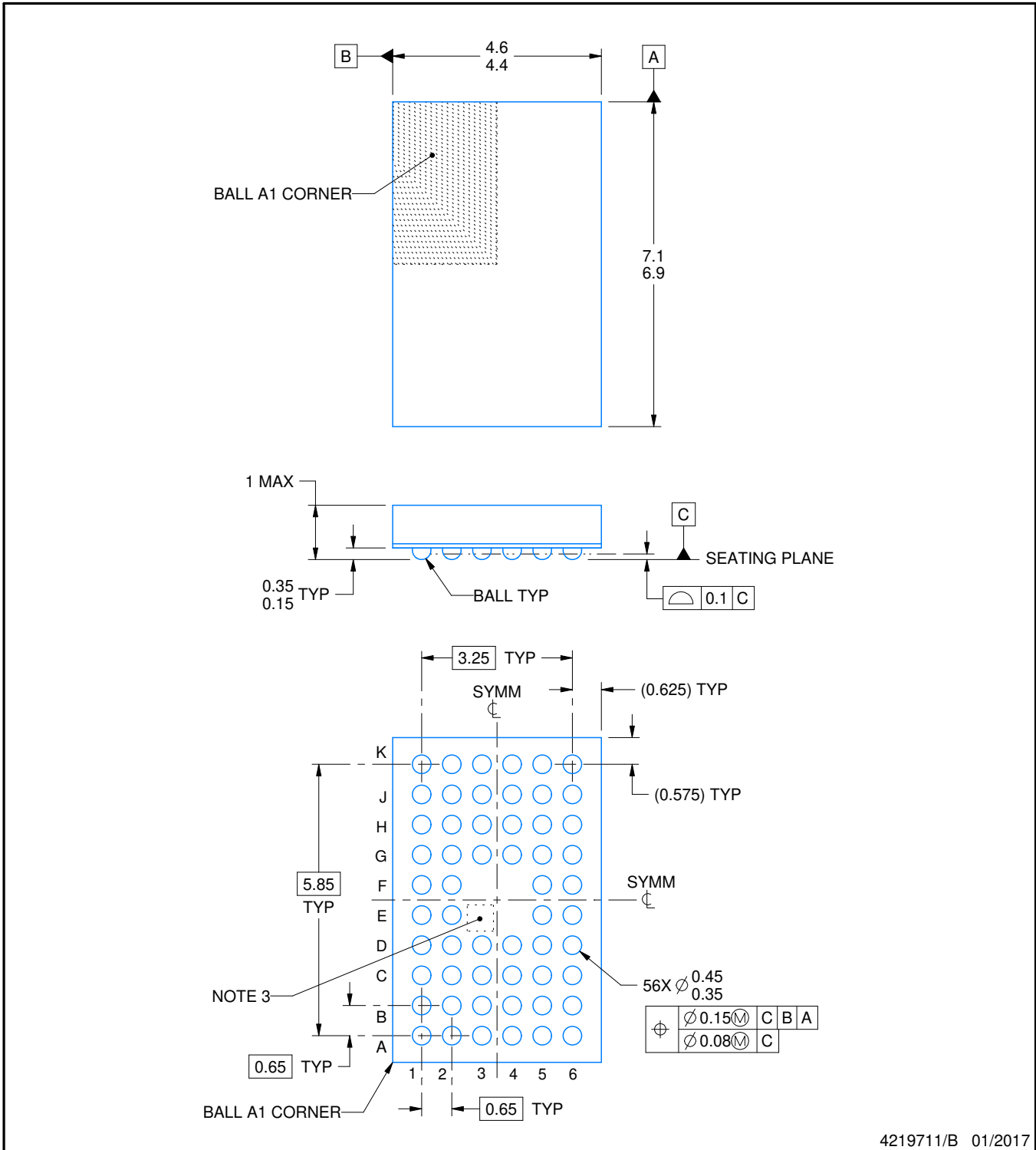
ZQL0056A



**PACKAGE OUTLINE**

**JRBGA - 1 mm max height**

PLASTIC BALL GRID ARRAY



4219711/B 01/2017

**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. No metal in this area, indicates orientation.

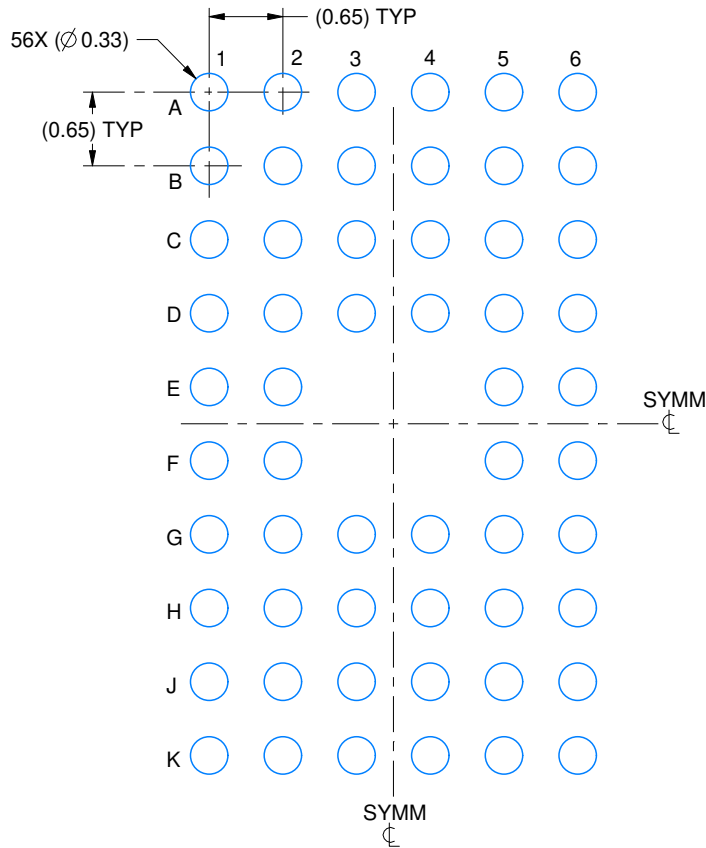


# EXAMPLE BOARD LAYOUT

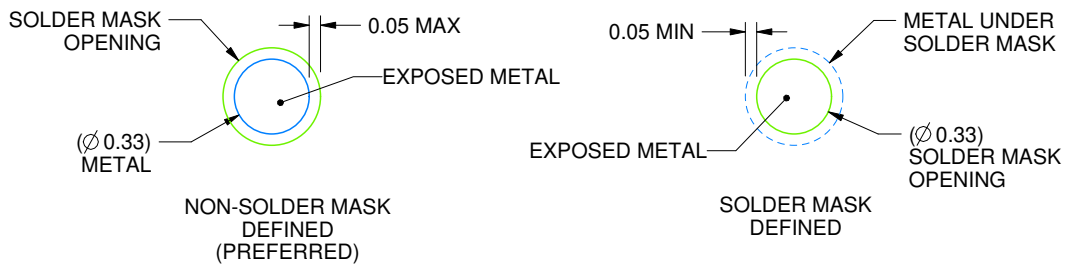
ZQL0056A

JRBGA - 1 mm max height

PLASTIC BALL GRID ARRAY



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS  
NOT TO SCALE

4219711/B 01/2017

NOTES: (continued)

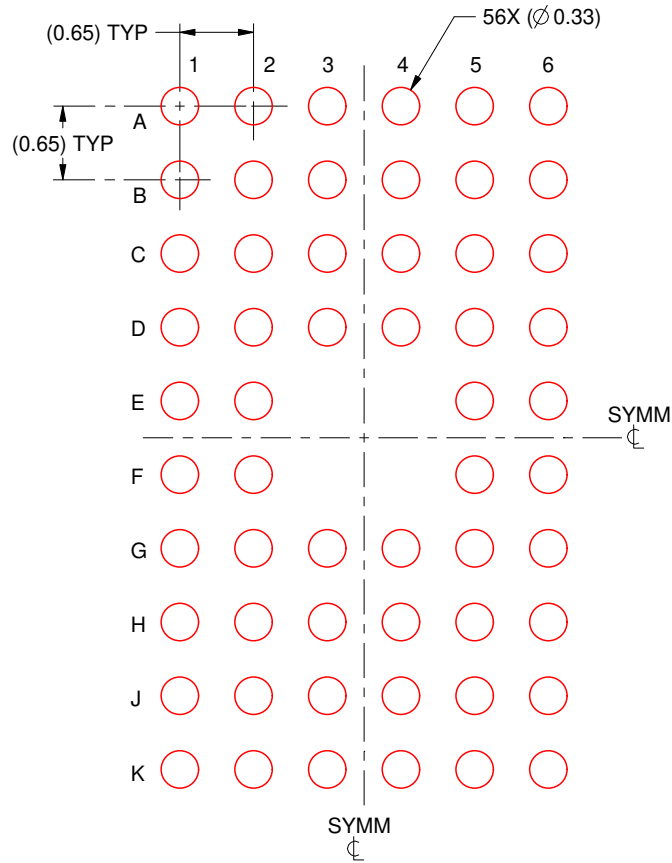
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRAA99 ([www.ti.com/lit/spraa99](http://www.ti.com/lit/spraa99)).

# EXAMPLE STENCIL DESIGN

ZQL0056A

JRBGA - 1 mm max height

PLASTIC BALL GRID ARRAY



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

4219711/B 01/2017

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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